15

20

## ABSTRACT

Disclosed herein are a mixed resin compound, a resin pipe, a process for producing said resin pipe, and a photosensitive drum. The resin compound meets at least one of the following requirements. It is a mixture of two or more kinds of resins blended in a specific manner, it undergoes annealing under specific conditions, and it has specific values of surface roughness, Vickers hardness, 10 coefficient of linear expansion, flexural modulus, and thermal conductivity. The resin pipe is suitable for use as the cylindrical base of the photosensitive drum for electrophotographic machines, such as copying machines, facsimiles, and printers. It is superior in surface smoothness, dimensional stability, coatability, and handlability, and hence it is very little vulnerable to damage during handling and dimensional change due to resin shrinkage and is superior in heat resistance (desirable for solvent removal) and mechanical strength (desirable for flange fitting).